

CLAIMS:

1. A silicone rubber adhesive composition comprising
  - (A) 100 parts by weight of a heat curable organopolysiloxane composition,
  - (B) 1 to 100 parts by weight of reinforcing silica fines, and
  - (C) 0.1 to 50 parts by weight of an organic compound or organosilicon compound having an epoxy equivalent of 100 to 5,000 g/mol and containing at least one aromatic ring in a molecule.
2. The composition of claim 1 wherein component (C) is an organosilicon compound containing at least one Si-H group in a molecule.
3. The composition of claim 1 which provides a greater bond strength to organic resins than to metals.
4. An integrally molded article comprising a silicone rubber adhesive composition in the cured state and a thermoplastic resin, said silicone rubber adhesive composition comprising
  - (A) 100 parts by weight of a heat curable organopolysiloxane composition,
  - (B) 1 to 100 parts by weight of reinforcing silica fines, and
  - (C) 0.1 to 50 parts by weight of an organic compound or organosilicon compound having an epoxy equivalent of 100 to 5,000 g/mol and containing at least one aromatic ring in a molecule.
5. The integrally molded article of claim 4 wherein component (C) is an organosilicon compound containing at least one Si-H group in a molecule.